

## WE CLAIM:

1. A method of fabricating an ink jet nozzle arrangement, the method comprising the steps, which can be carried out in any suitable order, of:  
providing a wafer;  
depositing and etching a plurality of permanent layers on one side of the wafer to form an ink ejection mechanism;  
anisotropically wet etching said wafer from said one side to form a nozzle chamber; and  
etching said wafer from an opposed side to form an ink supply channel in communication with the nozzle chamber for supplying ink to the nozzle chamber.
2. The method of claim 1 in which the wet etching includes crystallographically etching the wafer along predetermined planes.
3. The method of claim 2 which includes crystallographically etching the wafer along  $\langle 111 \rangle$  planes.
4. The method of claim 1 which includes plasma etching the wafer from said opposed side.
5. The method of claim 4 which includes using an anisotropic etcher for plasma etching the wafer.
6. The method of claim 1 in which the step of etching the wafer from said opposed side also dices the wafer.